



# UNITED STATES PATENT AND TRADEMARK OFFICE

UNITED STATES DEPARTMENT OF COMMERCE  
United States Patent and Trademark Office  
Address: COMMISSIONER FOR PATENTS  
P.O. Box 1450  
Alexandria, Virginia 22313-1450  
www.uspto.gov

APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
10/750,560	12/31/2003	David W. Boggs	111079-135918	5692

31817 7590 05/04/2006

SCHWABE, WILLIAMSON & WYATT  
PACWEST CENTER, SUITE 1900  
1211 S.W. FIFTH AVE.  
PORTLAND, OR 97204

EXAMINER

PATEL, ISHWARBHAI B

ART UNIT	PAPER NUMBER
----------	--------------

2841

DATE MAILED: 05/04/2006

Please find below and/or attached an Office communication concerning this application or proceeding.

## Office Action Summary

Application No.

10/750,560

Applicant(s)

BOGGS ET AL.

Examiner

Ishwar (I. B.) Patel

Art Unit

2841

-- The MAILING DATE of this communication appears on the cover sheet with the correspondence address --

### Period for Reply

A SHORTENED STATUTORY PERIOD FOR REPLY IS SET TO EXPIRE 3 MONTH(S) OR THIRTY (30) DAYS, WHICHEVER IS LONGER, FROM THE MAILING DATE OF THIS COMMUNICATION.

- Extensions of time may be available under the provisions of 37 CFR 1.136(a). In no event, however, may a reply be timely filed after SIX (6) MONTHS from the mailing date of this communication.
- If NO period for reply is specified above, the maximum statutory period will apply and will expire SIX (6) MONTHS from the mailing date of this communication.
- Failure to reply within the set or extended period for reply will, by statute, cause the application to become ABANDONED (35 U.S.C. § 133). Any reply received by the Office later than three months after the mailing date of this communication, even if timely filed, may reduce any earned patent term adjustment. See 37 CFR 1.704(b).

### Status

- 1) ☒ Responsive to communication(s) filed on 03 March 2006.
- 2a) ☒ This action is **FINAL**. 2b) ☐ This action is non-final.
- 3) ☐ Since this application is in condition for allowance except for formal matters, prosecution as to the merits is closed in accordance with the practice under *Ex parte Quayle*, 1935 C.D. 11, 453 O.G. 213.

### Disposition of Claims

- 4) ☒ Claim(s) 1-8 and 19-23 is/are pending in the application.
- 4a) Of the above claim(s) 9-18 is/are withdrawn from consideration.
- 5) ☐ Claim(s) \_\_\_\_\_ is/are allowed.
- 6) ☒ Claim(s) 1-8 and 19-23 is/are rejected.
- 7) ☐ Claim(s) \_\_\_\_\_ is/are objected to.
- 8) ☐ Claim(s) \_\_\_\_\_ are subject to restriction and/or election requirement.

### Application Papers

- 9) ☐ The specification is objected to by the Examiner.
- 10) ☐ The drawing(s) filed on 31 December 2003 is/are: a) ☒ accepted or b) ☐ objected to by the Examiner.  
Applicant may not request that any objection to the drawing(s) be held in abeyance. See 37 CFR 1.85(a).  
Replacement drawing sheet(s) including the correction is required if the drawing(s) is objected to. See 37 CFR 1.121(d).
- 11) ☐ The oath or declaration is objected to by the Examiner. Note the attached Office Action or form PTO-152.

### Priority under 35 U.S.C. § 119

- 12) ☐ Acknowledgment is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d) or (f).
- a) ☐ All b) ☐ Some \* c) ☐ None of:
- ☐ Certified copies of the priority documents have been received.
  - ☐ Certified copies of the priority documents have been received in Application No. \_\_\_\_\_.
  - ☐ Copies of the certified copies of the priority documents have been received in this National Stage application from the International Bureau (PCT Rule 17.2(a)).

\* See the attached detailed Office action for a list of the certified copies not received.

### Attachment(s)

- ☒ Notice of References Cited (PTO-892)
- ☐ Notice of Draftsperson's Patent Drawing Review (PTO-948)
- ☐ Information Disclosure Statement(s) (PTO-1449 or PTO/SB/08)  
Paper No(s)/Mail Date \_\_\_\_\_
- ☐ Interview Summary (PTO-413)  
Paper No(s)/Mail Date. \_\_\_\_\_
- ☐ Notice of Informal Patent Application (PTO-152)
- ☐ Other: \_\_\_\_\_

## DETAILED ACTION

1. This is response to an amendment filed on March 3, 2006.

### ***Claim Rejections - 35 USC § 102***

2. The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless –

(b) the invention was patented or described in a printed publication in this or a foreign country or in public use or on sale in this country, more than one year prior to the date of application for patent in the United States.

3. Claims 1-8 are rejected under 35 U.S.C. 102(b) as being anticipated by Shin (US Patent No. 6,405,431).

**Regarding claim 1**, Shin, in figure 6c, discloses an electronic substrate comprising: a substrate (substrate as shown in figure 6c) having two or more electrically conductive inner layer (layer with circuit patterns 62a' and 62a); and one cavity (69a, shown in more detail in figure 6b) interconnect cavity extending into, but not through, the substrate (see figure 6b, 6c), each exposing two of the electrically conductive inner layers (exposing layer with circuit patterns 62a' and 62a) and an interconnect material (plating material in the cavity, see figure 6c) disposed in part outside (part of the plating above the upper surface of substrate layer) of the interconnect cavities and in part inside the one interconnect cavity (part of the plating layer inside the cavity, see figure 6c), the interconnect material configured to electrically couple and simultaneously

contact each of a surface mount technology component and two or more of the electrically conductive inner layers (the plating material connecting two inner conductive layer and will connect the component when mounted).

**Regarding claim 2**, Shin further discloses one electrically conductive surface layer (layer with circuit pattern 64), wherein the interconnect cavity extends from the electrically conductive surface layer (layer with circuit pattern 64), to the electrically conductive inner layer (layer with circuit patterns 62a).

**Regarding claim 3**, Shin further discloses the interconnect cavity comprises a base (base of the cavity 69a on 62a) adjacent to the electrically conductive inner layer (layer with circuit pattern 62a), the base comprising a layer of electrically conductive material (base of the cavity 69a, formed by the plating layer, see figure 6c).

**Regarding claim 4**, Shin further discloses the interconnect cavity comprises a base (base of the cavity 69a) adjacent to the electrically conductive inner layer (62a), wherein the interconnect cavity defines a wall (wall of cavity 69a) interconnected with the base adjacent electrically conductive inner layer (62a).

**Regarding claim 5**, Shin further discloses the interconnect cavity comprises a base (base of the cavity 69a) adjacent to and electrically interconnected with the conductive inner layer (62a), the interconnect cavity extending from a surface layer (64)

Art Unit: 2841

defines a wall (wall of cavity 69a) interconnected with the base adjacent electrically conductive inner layer (62a) and the surface layer (64).

**Regarding claim 6**, Shin further discloses the interconnect cavity is adapted to receive and interconnect with electrically conductive interconnect material (see figure).

**Regarding claim 7**, Shin further discloses the interconnect cavities are positioned to correspond land pads of a surface mount technology electrical component (as the circuit board is for mounting components, column 2, line 13-16).

**Regarding claim 8**, Shin further discloses at least one of the interconnect cavities comprises a base (base of the cavity 69a) adjacent to the electrically conductive inner layer (62a) and an opening at a surface of the substrate, the base having a smaller diameter than the opening (base of the cavity 69a smaller than the opening, see figure 6c).

### ***Claim Rejections - 35 USC § 103***

4. The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:

(a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negated by the manner in which the invention was made.

5. Claims 19-23 are rejected under 35 U.S.C. 103(a) as being unpatentable over Shin as applied to claims 1-8 above, and further in view of Ho (US Patent No. 6,717,264).

**Regarding claim 19,** Shin, figure 6c, discloses an electronic device comprising: a substrate (substrate as shown in figure 6c) including two electrically conductive inner layers (layers with circuit pattern 62' and 62a); and one interconnect cavity (69a, shown in more detail in figure 6b) extending into a surface of, but not through the substrate (see figure 6b, 6c), exposing two electrically conductive inner layer (layers with circuit pattern 62' and 62a) and an interconnect material (plating material in the cavity, see figure 6c) disposed in part outside (part of the plating above the upper surface of substrate layer) of the interconnect cavities and in part inside the one interconnect cavity (part of the plating layer inside the cavity, see figure 6c), the interconnect material configured to electrically couple and simultaneously contact each of a surface mount technology component and two or more of the electrically conductive inner layers (the plating material connecting two inner conductive layer and will connect the component when mounted).

Shin does not disclose an electronic component, having component interconnects, mounted on the substrate. However, Shin in the background states that the substrate structure is for mounting the components, column 1, line 1-30. Further, it is old and known in the art to use the substrate for mounting the component, wherein the substrate facilitates the interconnection of the devices. Also, component mounted on

Art Unit: 2841

a substrate can be seen by opening of any electronic device such as computer etc. Ho, in figure 4F, discloses a component (300) with component interconnect (310), mounted on the substrate for desired interconnection for the functioning of the device.

Therefore, it would have been obvious to a person of ordinary skill in the art at the time of applicant's invention to mount a component on the substrate of Shin, in order to facilitate interconnection between the component for the functionality of the devices, as taught by Ho.

**Regarding claim 20**, the modified assembly of Shin further discloses the substrate further comprises one electrically conductive surface layer (64), wherein one of the interconnect cavity (69a, shown in more detail in figure 6b) extends from at least one of the surface layer to the electrically conductive inner layer (62a').

**Regarding claim 21**, the modified assembly of Shin further discloses at least one of the interconnect cavities comprises a base (base of the cavity 69a) adjacent to the electrically conductive inner layer (62a), the base comprising a layer of electrically conductive material (base of the cavity 69a, formed by the plating layer, see figure 6c).

**Regarding claim 22**, the modified assembly of Shin further discloses at least one of the interconnect cavities comprises a base (base of the cavity 69a) adjacent to the electrically conductive inner layer (62a), wherein the interconnect cavity defines a wall (wall of cavity 69a) interconnected with the base adjacent conductive

Art Unit: 2841

inner layer (62a).

**Regarding claim 23**, the modified assembly of Shin further discloses the electronic component is a microelectronic die (300, Ho).

### ***Response to Arguments***

6. Applicant's arguments with respect to claim 1-8 and 19-23 have been considered but are moot in view of the new explanation / new ground(s) of rejection.

### ***Conclusion***

7. The prior art made of record and not relied upon is considered pertinent to applicant's disclosure.

Zollo (US Patent No. 6,972,382), in prior art figure 2, discloses a substrate with cavity (cavity in the middle of the figure) in the substrate exposing two internal conductive layers.

Alcoe (US Patent No. 6,992,379), in figure 3, discloses a component (54) mounted on a substrate).

8. Applicant's amendment necessitated the new ground(s) of rejection presented in this Office action. Accordingly, **THIS ACTION IS MADE FINAL**. See MPEP



Art Unit: 2841

§ 706.07(a). Applicant is reminded of the extension of time policy as set forth in 37 CFR 1.136(a).

A shortened statutory period for reply to this final action is set to expire THREE MONTHS from the mailing date of this action. In the event a first reply is filed within TWO MONTHS of the mailing date of this final action and the advisory action is not mailed until after the end of the THREE-MONTH shortened statutory period, then the shortened statutory period will expire on the date the advisory action is mailed, and any extension fee pursuant to 37 CFR 1.136(a) will be calculated from the mailing date of the advisory action. In no event, however, will the statutory period for reply expire later than SIX MONTHS from the date of this final action.

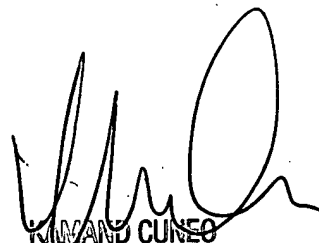
Any inquiry concerning this communication or earlier communications from the examiner should be directed to Ishwar (I. B.) Patel whose telephone number is (571) 272 1933. The examiner can normally be reached on M-F (8:30 - 5:00).

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Kamand Cuneo can be reached on (571) 272 1957. The fax phone number for the organization where this application or proceeding is assigned is 571-273-8300.

Art Unit: 2841

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see <http://pair-direct.uspto.gov>. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

Ishwar (I. B.) Patel  
Patent Examiner  
Art Unit: 2841  
April 21, 2006



**RICHARD CUNEO**  
SUPERVISORY PATENT EXAMINER  
TECHNOLOGY CENTER 2800